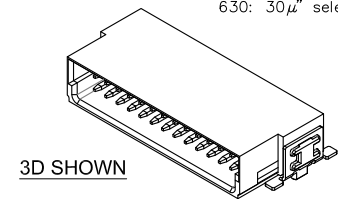


< ORDERING INFORMATION >

SERIES NO. SMC03 XX XXX 3  
 1.27 SMC Male Connector  
 Right Angle SMT Type  
 CONTACT POSITION See DIM-TABLE

PACKAGE 3: Tape & Reel  
 CONTACT PLATING  
 600: Selective Gold Flash Plated (1μ" Min.)  
 605: 5μ" selective Gold Plated  
 630: 30μ" selective Gold Plated



**Specification**  
 Insulator Material: High Temp. Thermoplastic, UL94V-0.  
 Contact Material: Phosphor Bronze.  
 Board Lock Material: Brass.  
 Contact Plating: Au on Contact Area.  
 Sn (100μ" Min.) on Solder-tail.  
 Nickel (Contact - 80μ" Min. / Solder-tail - 50μ" Min.)  
 Board Lock Plating: Sn(100μ" Min.) over Nickel (40μ" Min.)  
 Current Rating: 1.2A Max.  
 Contact Resistance: 25 Milliohms Max.  
 Insulator Resistance: 1000 Megohms Min.  
 Dielectric Withstanding: 500V AC for 1 Minute.  
 Operating Temperature: -55°C ~ +125°C.  
 Max. Processing Temp.: 230°C for 30~60 seconds.  
 260°C for 10 seconds.

DIM-TABLE

PIN NO.	DIM A	DIM B	DIM C	DIM D	DIM E	DIM F	DIM G
10	11.43	7.30	5.08	8.30	9.50	10.07	9.10
12	12.70	8.57	6.35	9.57	10.77	11.34	10.37
16	15.24	11.11	8.89	12.11	13.31	13.88	12.91
20	17.78	13.65	11.43	14.65	15.85	16.42	15.45
24	20.32	16.19	13.97	17.19	18.39	18.96	17.99
26	21.59	17.46	15.24	18.46	19.66	20.23	19.26
30	24.13	20.00	17.78	21.00	22.20	22.77	21.80
32	25.40	21.27	19.05	22.27	23.47	24.04	23.07
40	30.48	26.35	24.13	27.35	28.55	29.12	28.15
50	36.83	32.70	30.48	33.70	34.90	35.47	34.50
68	48.26	44.13	41.91	45.13	46.33	46.90	45.93
80	55.88	51.75	49.53	52.75	53.95	54.52	53.55

REV.	DESCRIPTION	DATE
DR. Shun	CHK. Ren	APP. Peter
△	Add "Pin No" Option	2020,02,25
△	New Version	2019,03,20



TOLERANCE (UNLESS SPECIFIED)
0.0 ±0.35
0.00 ±0.20
0.000 ±0.10
ANG. ±2°



TITLE: 1.27 SMC Male Connector  
 Right Angle SMT Type

DWG NO. SMC03\_C  
 FILE PATH SMC\BTB\SMC03\_CB

SHEET 1 / 1  
 REV. B